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2 Name and address of receiving party(ies):
Taiwan Semiconductor Manufacturing Co. Ltd. No. 121 Park Avenue 3 Science-Based Industrial Park Hsin-Chu, Taiwan, R.O.C.
Additional name(s) & address(es) attached □ Yes ☑ No
tion, the execution date of the application is: <u>07-29-02</u>
B. Patent No(s)
attached? □ Yes ⊠ No
6 Total number of applications and patents involved:
7 Total fee (37 CFR 3.41) \$40.00
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ormation is true and correct and any attached copy is a true copy of
April 24, 2003
April 2 1, 2009
Date

Washington, D.C. 20231

ASSIGNMENT

WHEREAS, we, SHEN-NAN LEE, YING-HO CHEN, SYUN-MING JANG, TZU-

JEN CHOU and JIN-YIING SONG, have invented certain improvements in

METHOD TO REDUCE DISHING AND EROSION IN A CMP PROCESS

for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of

No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of

acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and

valuable consideration, the receipt of which is hereby acknowledged, we, SHEN-NAN LEE, YING-

HO CHEN, SYUN-MING JANG, TZU-JEN CHOU and JIN-YIING SONG, by these presents, do

hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the

United States of America and all foreign countries, the entire right, title and interest, including all

priority rights under the International Convention associated with each country of the Union, in and

to said invention as described in the patent application executed by us on the 29 day of

July, 2002, preparatory to obtaining Letters Patent of the United States thereon,

and in and to said application and any Letters Patent that may be granted in pursuance of said

application and any divisional, continuation or continuation-in-part application thereof, and in and

to any reissue of any such patent, and in and to any patent applications which may be filed on said

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PATENT REEL: 014019 FRAME: 0702 67,200-924 2002-0215

invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Shen-Nan Lee

YING-HOCHEN

Tzu-Jen Chou
TZU-JEN CHOU

Jin- Ying Song
JIN/YIING SONG

RECORDED: 04/24/2003

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

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PATENT REEL: 014019 FRAME: 0703